Processing Materials of 3D Interconnects, Damascene and Electronics Packaging 8

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Table of Contents

Preface *iii*

Chapter 1
TSV

(Invited) Semiconductor Packaging Technology to Progress the IoT Era 3
Y. Takeno

Chapter 2
Additive Chemistry

A Novel Bottom up Fill Mechanism for the Metallization of Advanced Node Copper Interconnects 9
V. Mevellec, M. Thiam, D. Suhr, L. Religieux, P. Blondeau, J. B. Chaumont, F. Raynal

The Suppression Induced S-NDR Mechanism for Defect-Free Filling of High Aspect Ratio Features 15
D. Josell, T. P. Moffat

Chapter 3
Electrodeposition

Electroplating through Fluidic Channels as Production Technology for 3D Interconnect Devices and Sensing Structures 25
M. Rechel, S. Bengsch, M. C. Wurz

Invar Electroplating for Controlled Expansion Interconnects 33
V. M. Dubin, M. O. Lisunova, I. O. Kovalenko, B. L. Walton, G. Downey, J. Su, K. Witt

Chapter 4
Others

Copper Oxide Direct Bonding of 200mm CMOS Wafers with Five Metal Levels and TSVs: Morphological and Electrical Characterization 43
C. Cavaco, L. Peng, S. Lavizzari, J. Claes, N. V. Hoovels, S. Guerrieri, D. S. Tezcan, H. Osman

Author Index 47